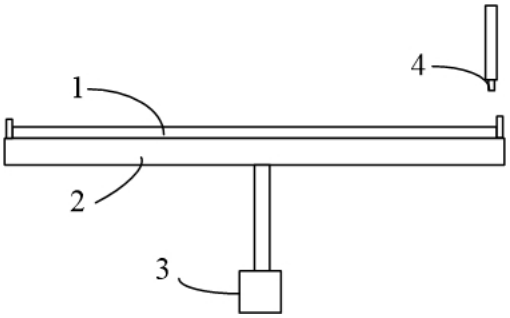

4
1
2
3

FIG. 1

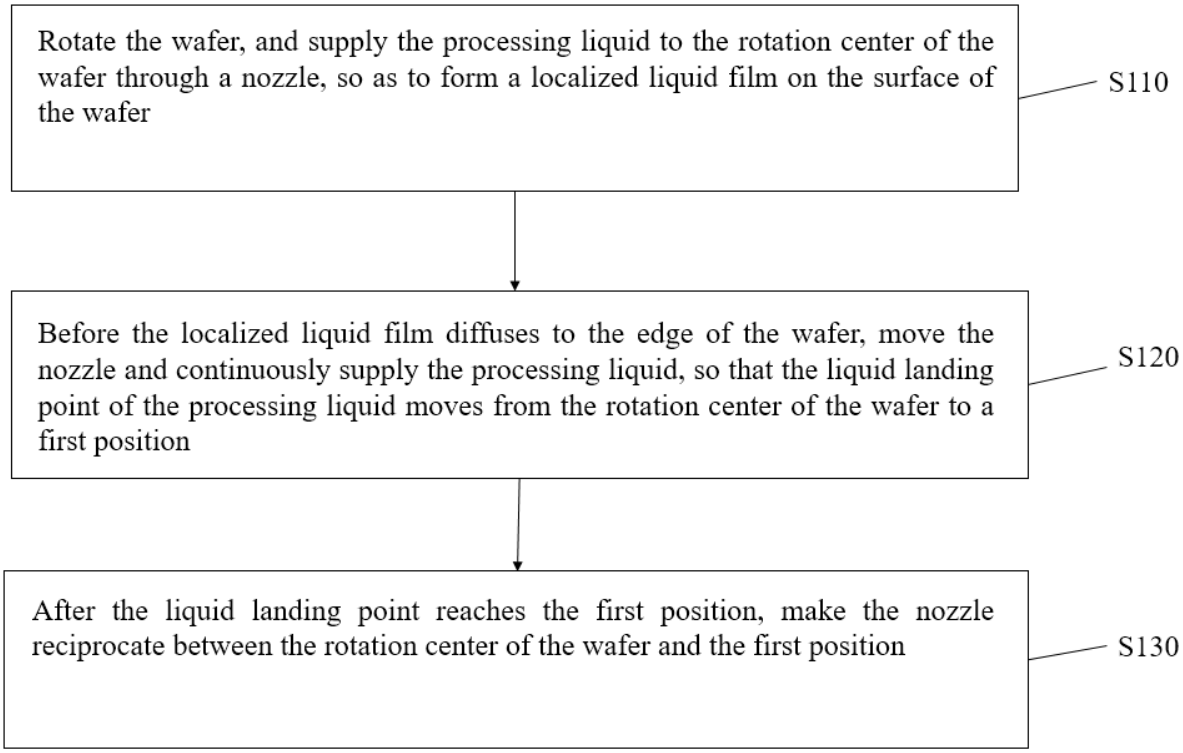

Rotate the wafer, and supply the processing liquid to the rotation center of the wafer through a nozzle, so as to form a localized liquid film on the surface of the wafer
S110
Before the localized liquid film diffuses to the edge of the wafer, move the nozzle and continuously supply the processing liquid, so that the liquid landing point of the processing liquid moves from the rotation center of the wafer to a first position
S120
After the liquid landing point reaches the first position, make the nozzle reciprocate between the rotation center of the wafer and the first position
S130

FIG. 2

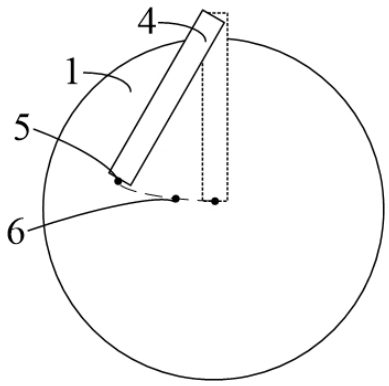

4
1
5
6

FIG. 3

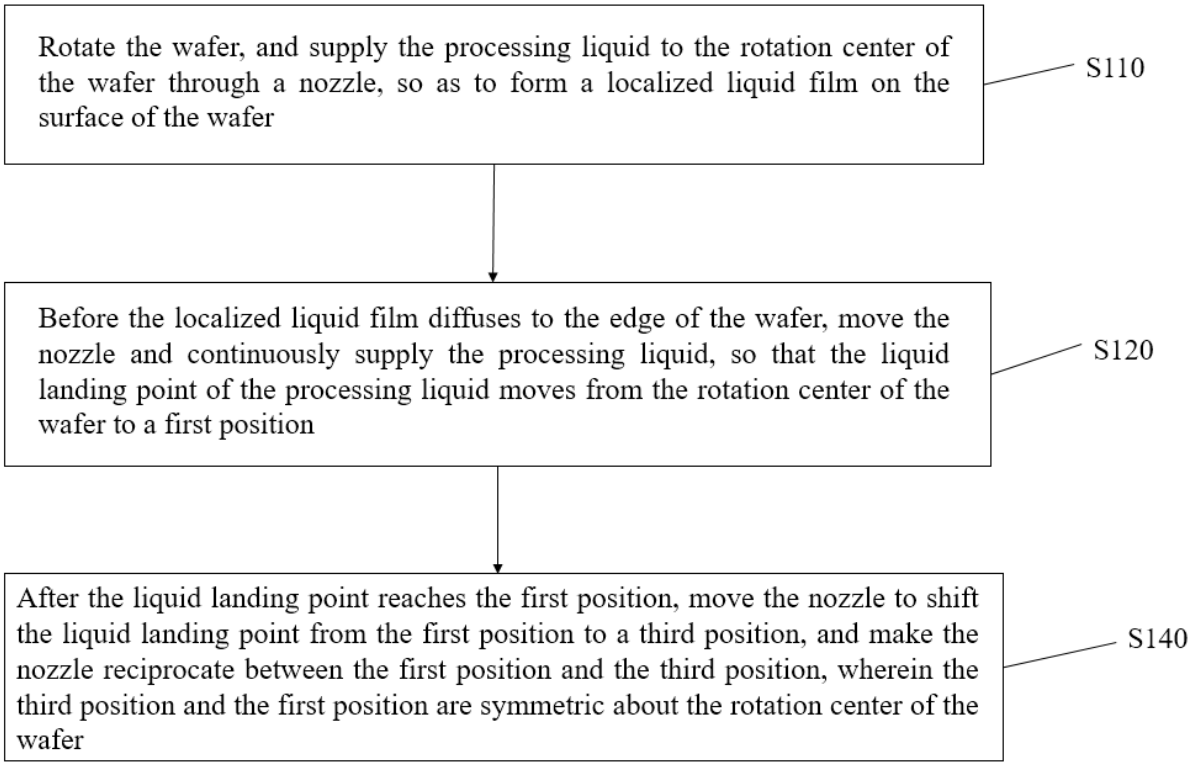

Rotate the wafer, and supply the processing liquid to the rotation center of the wafer through a nozzle, so as to form a localized liquid film on the surface of the wafer
S110
Before the localized liquid film diffuses to the edge of the wafer, move the nozzle and continuously supply the processing liquid, so that the liquid landing point of the processing liquid moves from the rotation center of the wafer to a first position
S120
After the liquid landing point reaches the first position, move the nozzle to shift the liquid landing point from the first position to a third position, and make the nozzle reciprocate between the first position and the third position, wherein the third position and the first position are symmetric about the rotation center of the wafer
S140

FIG. 4

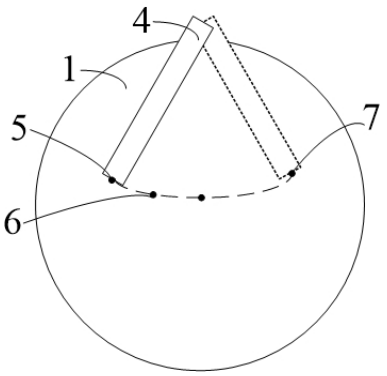

4
1
5
7
6

FIG. 5

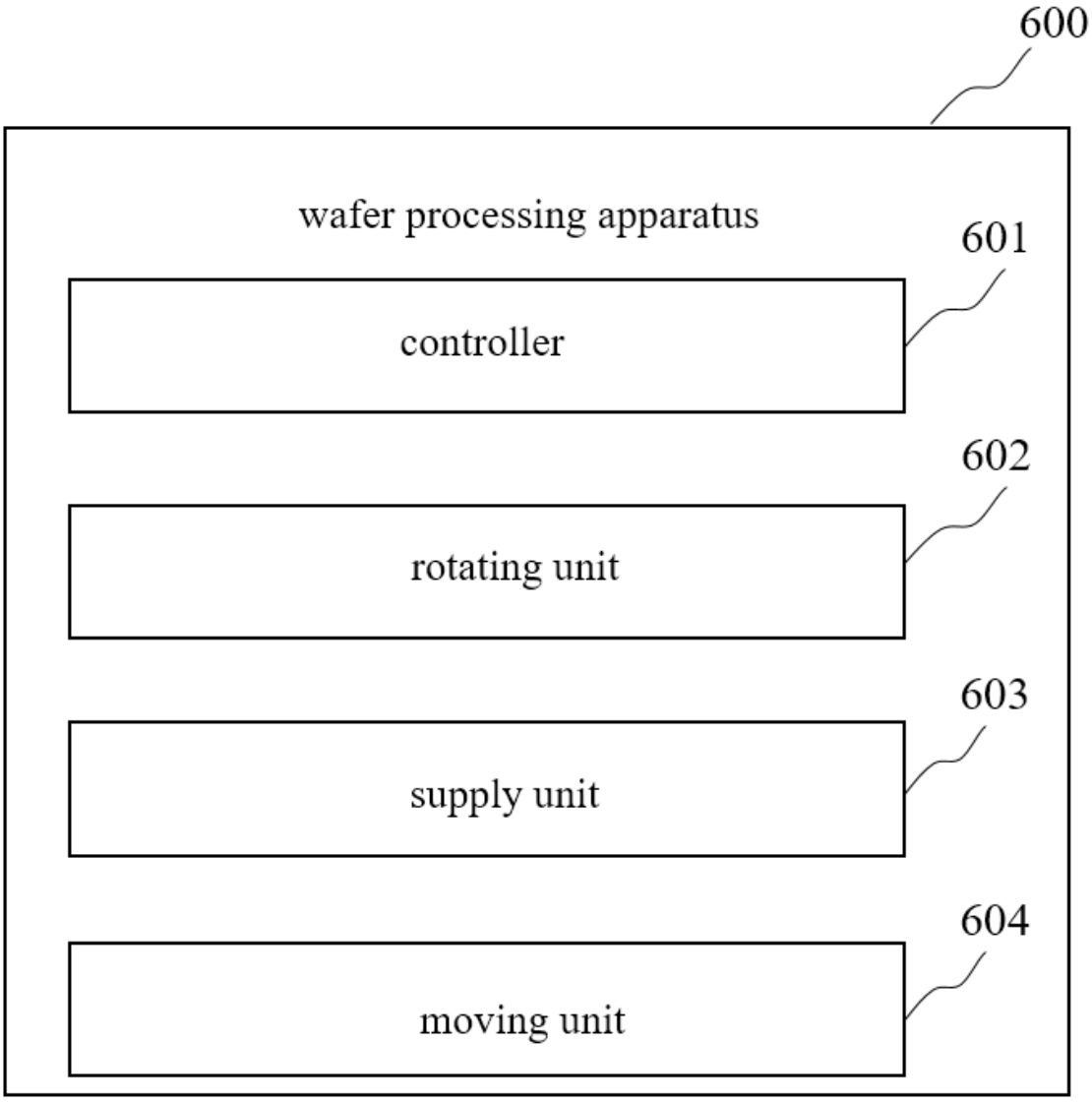

600
wafer processing apparatus
601
controller
602
rotating unit
603
supply unit
604
moving unit

FIG. 6